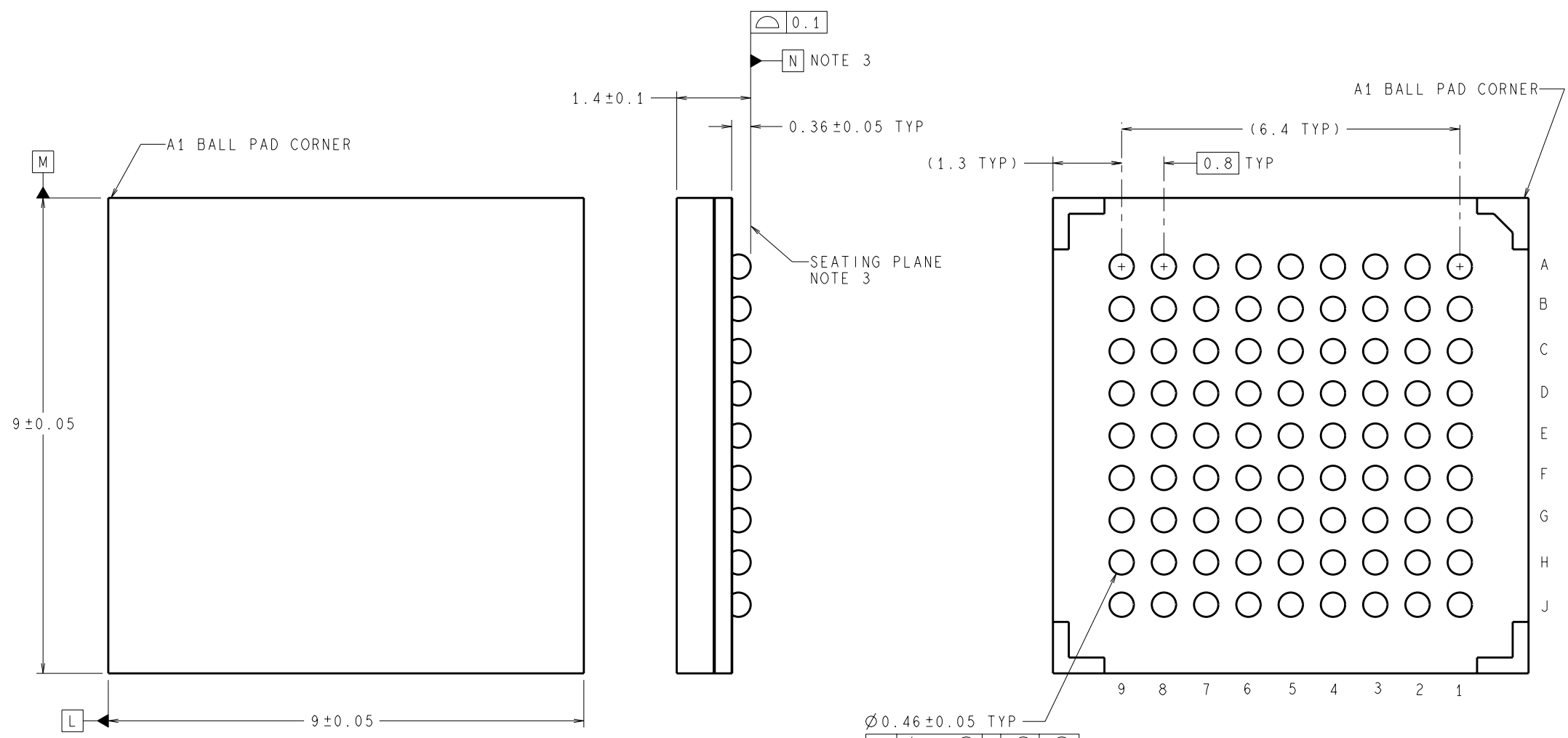


REVISIONS				
LTR	DESCRIPTION	E.C.N.	DATE	BY/APP'D
A	RELEASE TO DOCUMENT CONTROL	12252	07/08/1999	TL/



DIMENSIONS ARE IN MILLIMETERS

NOTE 2

\varnothing	0.15	M	N	L	S	M	S
\varnothing	0.08	M	N				

- NOTES: UNLESS OTHERWISE SPECIFIED
1. SOLDER BALL COMPOSITION: Sn 63%, Pb 37%.
 2. DIMENSION MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM N.
 3. PRIMARY DATUM N AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
 4. NO JEDEC REGISTRATION AS OF JULY 1999.

APPROVALS	DATE	National Semiconductor		
DRAWN T. LEQUANG	07/08/1999	2900 Semiconductor dr., Santa Clara, CA 95052-8090		
DFTG. CHK.		FBGA, PLASTIC, LAMINATED, 0.8mm PITCH, 9 X 9 X 1.4mm, 81 BALL		
ENGR. CHK.		SCALE	SIZE	DRAWING NUMBER
		N/A	C	(SC)MKT-SLC81A
		DO NOT SCALE DRAWING		REV A
		SHEET 1 of 1		